



Reportable Substances in Components

Package Type :	SOIC (0.150")	Component Weight :	0.1522 grams
Lead #:	14	Document No :	SOICN-14LD-PBY-RS-3
		Process Type :	Standard D/A & Pb Free Lead Finish

No	Material	Content in %	Content in gram	Substance Name	CAS No	Content in gram	% to Content	% to Unit	PPM
1	Molding Compound	61.61%	0.093799						
				Silica Fused	60676-86-0	0.081324	86.70%	53.42%	
				Epoxy Resin	Trade secret	0.005628	6.00%	3.70%	
				Epoxy, Cresol Novolac	29690-82-2	0.001876	2.00%	1.23%	
				Phenol Resin	Trade secret	0.004690	5.00%	3.08%	
	Carbon Black	1333-86-4	0.000281	0.30%	0.18%				
2	Copper Alloy Frame	35.50%	0.054039						
				Cu	7440-50-8	0.052689	97.50%	34.61%	
				Fe	7439-89-6	0.001270	2.35%	0.83%	
				Zn	7440-66-6	0.000065	0.12%	0.04%	426
	P	7723-14-0	0.000016	0.03%	0.01%	106			
3	Spot Silver Plating	0.34%	0.000513						
				Ag	7440-22-4	0.000513	100.00%	0.34%	
3	Silver Die Attach Epoxy	0.10%	0.000156						
				Silver	7440-22-4	0.000122	78.00%	0.08%	801
				Epoxy Resin	Trade secret	0.000025	16.00%	0.02%	164
				Aromatic Amine	Trade secret	0.000009	6.00%	0.01%	62
4	Gold Wire	0.27%	0.000411						
				Au	7440-57-5	0.000411	100.00%	0.27%	
5	External Lead Plating	0.98%	0.001488						
				Sn	7440-31-5	0.001488	100.00%	0.98%	
6	Silicon Die	1.21%	0.001838						
				Si	7440-21-3	0.001838	100.00%	1.21%	

Rev	ECN	Originator	Change	Reason
A	090804SB07	E. Yoon	New release.	New
B	112806HC26	E. dISantos	Amend CAS no. of SiO2	Per Kamie S.
C	111109PM01	Alex Kungo	Change to Halogen-Free Molding Compound	Per Kamie S.